MULTILAYER CERAMIC ANTENNA FOR BLUETOOTH/WLAN IEEE 802.11b & WLAN IEEE 802.11a (2.45/5.2GHz) (Surface Mounted Ceramic Dual Band Antenna)

Product Specification¹ (Preliminary)

QUICK REFERENCE DATA		
Dimension	8.7* 8 * 0.9 mm	
Central Frequency*	2.45 GHz /5.2GHz	
Bandwidth	>100 MHz	• •
Gain*	0 dBi max	
VSWR	2.5 max	
Polarization	Linear	
Azimuth	Omni-directional	0 1 2 3
Impedance	50Ω	
Operating Temperature	-55~125 °C	
Termination	Ni/Sn (Environmentally-F	riendly Leadless)
Resistance to soldering heat	260 ⁰ C, 10 sec.	
Maximum Power	1W	
* Actual value will depend on size of cust	omer ground plane	

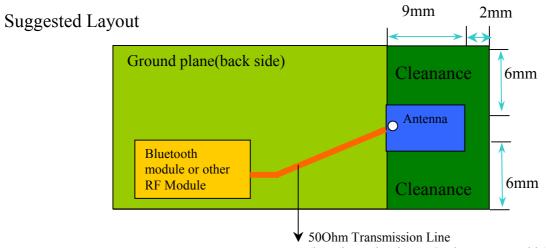


Special Environmental Concerns- Green Products Design: The foil making process is using environmentally-friendly aqueous solvent technology. Termination is lead free (Pb free) and packing materials can be re-cycled

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¹ All the technical data and information contained herein are subject to change without prior notice

APPLICATION



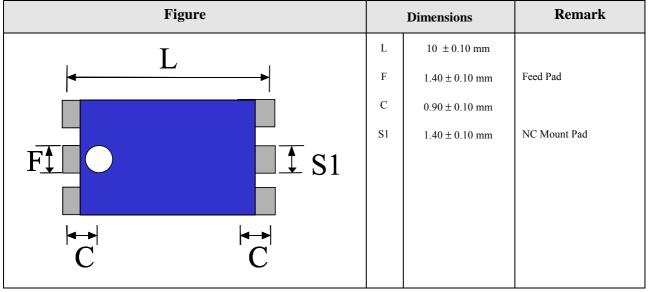
(by Microstrip Line or Coplanar Waveguide)

DIMENSIONAL DATA

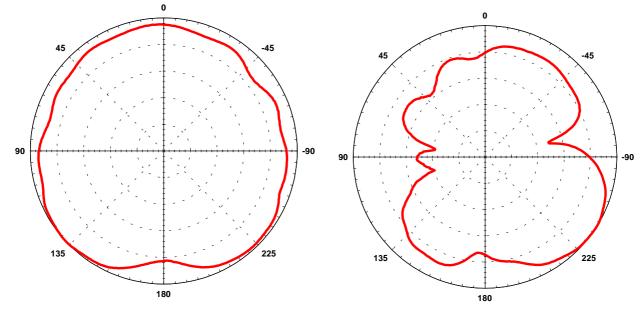
Figure	Dimension	Port		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	L 8.7 ±0.25 mm W 8 ±0.2 mm T 0.9 ±0.2 mm F 1.25 ±0.25 mm C 0.5 ±0.3 mm S1 1.25 ±0.35 mm	- - Feed Termination - NC Solder Termination		

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SOLDER LAND PATTERN



Typical Radiation Pattern Polar Plot (Based on Suggested Layout)

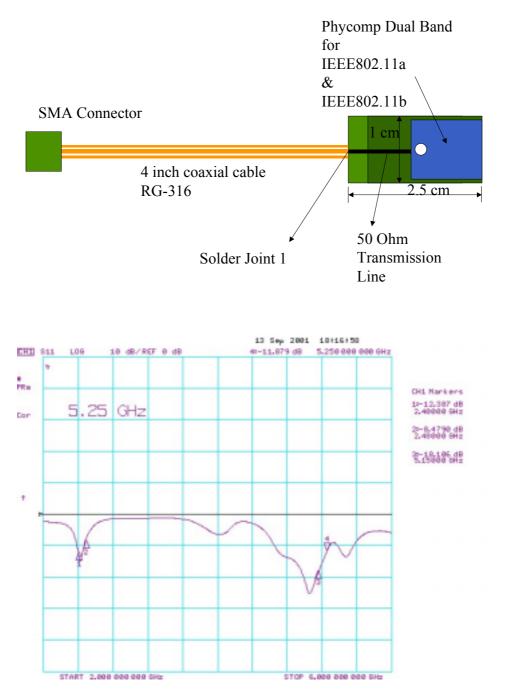


H-Plane

E-Plane

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IEC 384-10/ CECC 32 100 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS
4.4		Mounting	The antenna can be mounted on printed- circuit boards or ceramic substrates by applying wave soldering, reflow soldering (including vapour phase soldering) or conductive adhesive	No visible damage
4.5		Visual inspection and dimension check	Any applicable method using × 10 magnification	In accordance with specification (chip off 4mm)
4.6.1		Antenna	Frequency = $2.45/5.2$ GHz; at 20 °C	Standard test board in page 4
4.8		Adhesion	A force of 3 N applied for 10 s to the line joining the terminations and in a plane parallel to the substrate	No visible damage
4.9		Bond strength of plating on end face	Mounted in accordance with CECC 32 100, paragraph 4.4	No visible damage
			Conditions: bending 0.5 mm at a rate of 1mm/s, radius jig. 340 mm, 2mm warp on FR4 board of 90 mm length	No visible damage

RELIABILITY DATA (Reference to IEC Specification)

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IEC 384-10/ CECC 32 100 CLAUSE	IEC 60068-2 TEST METHOD	TEST	PROCEDURE	REQUIREMENTS
4.10	20(Tb)	Resistance to soldering heat	260 ± 5 °C for 10 ± 0.5 s in a static solder bath	The terminations shall be well tinned after recovery and Central Freq. Change ± 6%
		Resistance to leaching	260 ± 5 °C for 30 ± 1 s in a static solder bath	Using visual enlargement of \times 10, dissolution of the termination shall not exceed 10%
4.11	20(Ta)	Solderability	Zero hour test, and test after storage (20 to 24 months) in original atmosphere; un-mounted chips completely immersed for 2 ± 0.5 s in 235 ± 5°C.	The termination must be well tinned, at least 75% is well tinned at termination
4.12	4(Na)	Rapid change of temperature	-55 °C (30 minutes) to +125 °C (30 minutes); 100 cycles	No visible damage Central Freq. Change ± 6%
4.14	3(Ca)	Damp heat	500 ± 12 hours at 60 °C; 90 to 95 % RH	No visible damage 2 hours recovery Central Freq. Change ± 6%
4.15		Endurance	500 ± 12 hours at 125 °C;	No visible damage 2 hours recovery Central Freq. Change ± 6%

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ORDERING INFORMATION: Method I- by 12NC Ordering Code

The antennas may be ordered by using the 12 NC ordering code. These code numbers can be determined by the following rules:

 $\frac{4313}{F} \frac{117}{C} \frac{00}{T} \frac{252}{A}$ F. Family Code 43 = AntennaC. Packing Type Code 13 = 180 mm / 7" blister (1000pcs)M. Materials Code 1 = High Frequency MaterialS. Size Code 17 = 8.7 * 8 * 0.9 mmT. Tolerance

 $\mathbf{00} = 100 \text{ M Hz Band Width}$

A. Working Frequency

252 = 2.45/5.2 GHz Dual Band

Example: 12NC4313 117 00252Product description: Antenna (43) by 180 mm blister (11) of High
Frequency Material (1), Size 8.7*8*0.9 mm (17);
Tolerance (00) of 100 MHz (VSWR<2.5)
Working Frequency (252) = 2.45/5.2G Hz Dual Band

ORDERING INFORMATION: Method II- by Clear Text Code

The antennas may be ordered by using the 16-digit clear text ordering code. These code numbers can be determined by the following rules:

AN2520000708081K (Clear Text Code Example)									
2520	00	07	0808	1	K				
Central Freq.	Bandwidth	Material	Size	Quantities	Packing				
2520=2.45GHz	00 = >100 MHz	07=K7	0808=8.7*8*	1 = 1 K	K=7" plastic				
+ 5.2GHz			0.9 mm	4 = 4K					
	2520 Central Freq. 2520=2.45GHz	2520 00 Central Freq. Bandwidth 2520=2.45GHz 00=>100MHz	$\begin{array}{c cccc} 2520 & 00 & 07 \\ \hline Central Freq. & Bandwidth & Material \\ 2520=2.45 \mathrm{GHz} & 00=>100 \mathrm{MHz} & 07=\mathrm{K7} \end{array}$	2520 00 07 0808 Central Freq. Bandwidth Material Size 2520=2.45GHz 00=>100MHz 07=K7 0808=8.7*8*	2520 00 07 0808 1 Central Freq. Bandwidth Material Size Quantities 2520=2.45GHz 00=>100MHz 07=K7 0808=8.7*8* 1 = 1K				

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